



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-11-24
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L4995RJTR	A6WL*UH65AA6	A	BO2A	2014-11-24
Amount	UoM	Unit type	ST ECOPACK Grade	
82.40	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	4.9x3.9x1.35	12	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7a' exemption (other selected exemptions may apply)	TRUE
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A6WL*UH5AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.894	mg	supplier	die	Silicon (Si)	7440-21-3		3.654	mg	938367	44345
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	6934	328
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1027	49
Die				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.006	mg	1541	73
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.074	mg	19004	898
Die				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	514	24
Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1541	73
Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.019	mg	4879	231
Die				supplier	glass coating	Glass: Silicon Dioxide (SiO2)	7631-86-9		0.074	mg	19004	898
Die				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.028	mg	7191	340
Leadframe	Copper & its alloys	31.023	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.160	mg	939948	353883
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.686	mg	22113	8325
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.041	mg	1322	498
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.036	mg	1160	437
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		1.100	mg	35458	13350
Die attach		3.305	mg	JIG - R	Soft Solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	3.156	mg	954917	38301
Die attach				supplier	Soft Solder	Silver (Ag)	7440-22-4		0.083	mg	25113	1007
Die attach				supplier	Soft Solder	Tin (Sn)	7440-31-5		0.066	mg	19970	801
Bonding wire		0.158		supplier	wire	Gold (Au)	7440-57-5		0.158	mg	1000000	1917
encapsulation		42.617	mg	supplier	mold compound	Silica, vitreous	60676-86-0		34.095	mg	800033	413774
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		2.983	mg	69996	36201
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		1.704	mg	39984	20680
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		2.557	mg	60000	31032
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		0.511	mg	11991	6201
encapsulation				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		0.639	mg	14994	7755
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.128	mg	3003	1553
connections coating	Solder	1.403	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.403	mg	1000000	17027